Innovative Service Around the Globe YAGEO

DATA SHEET

SURFACE MOUNT MULTILAYER CERAMIC CAPACITORS

Automotive grade
with Soft Termination

X7R

10 V to 250 V

1 nF to 4.7 uF

RoHS compliant & Halogento Free

YAGEO
Phycomp

Product Specification – October 5, 2017 V.0

SCOPE

This specification describes Automotive grade X7R series chip capacitors with flexible lead-free terminations and used for automotive equipments.

APPLICATIONS

All general purpose applications
Entertainment applications
Comfort / security applications
Information applications

FEATURES

- AEC-Q200 qualified
- MSL class: MSL 1
- AC series soldering is compliant with J-STD-020D
- Halogen free epoxy
- RoHS compliant
- Reduce environmentally hazardous waste
- High component and equipment reliability
- Save PCB space
- The capacitors are 100% performed by automatic optical inspection prior to taping.

ORDERING INFORMATION - GLOBAL PART NUMBER

All part numbers are identified by the series, size, tolerance, TC material, packing style, voltage, process code, termination and capacitance value.

GLOBAL PART NUMBER

AS	XXXX	X	X	XXX	X	B	X	XXX
	(1)	(2)	(3)	(4)	(5)		(6)	(7)

(1) SIZE – INCH BASED (METRIC)

0805 (2012) / 1206 (3216)/ 1210 (3225)

(2) TOLERANCE

J = ±5%
K = ±10%
M= ±20%

(3) PACKING STYLE

R = Paper/PE taping reel; Reel 7 inch
K = Blister taping reel; Reel 7 inch
P = Paper/PE taping reel; Reel 13 inch
F = Blister taping reel; Reel 13 inch

(4) TC MATERIAL

X7R

(5) RATED VOLTAGE

8 = 25 V
9 = 50 V
0 = 100 V
A = 200 V
Y = 250 V

(6) PROCESS

B = Class 2 MLCC

(7) CAPACITANCE VALUE

2 significant digits+number of zeros
The 3rd digit signifies the multiplying factor, and letter R is decimal point
Example: 121 = 12 x 10^1 = 120 pF

CONSTRUCTION

The capacitor consists of a rectangular block of ceramic dielectric in which a number of interleaved metal electrodes are contained. This structure gives rise to a high capacitance per unit volume.

The inner electrodes are connected to the two end flexible terminations and finally covered with a layer of plated tin (NiSn).

The terminations are lead-free. A cross section of the structure is shown in Fig.1 and Fig.2.

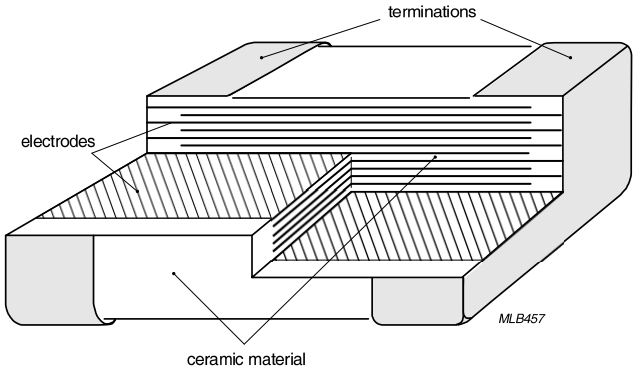
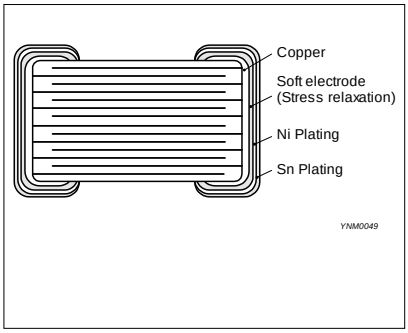


Fig. 1 Surface mounted multilayer ceramic capacitor construction

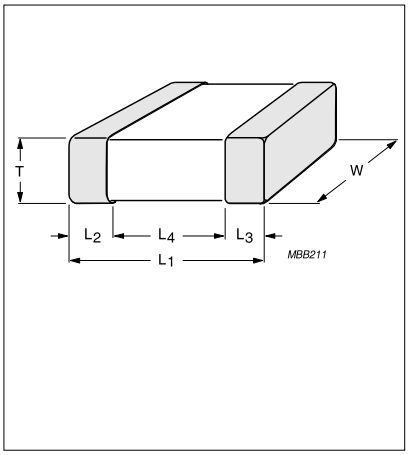


DIMENSION

Table 1 For outlines see fig. 3

TYPE	L1 (mm)	W (mm)	T (mm)	L2/L3(mm) min	L2/L3(mm) max	L4(mm) min
0805	2.0 ± 0.3	1.25 ± 0.2	0.85 ± 0.15	0.25	0.75	0.70
			1.25 ± 0.20			
1206	3.2 ± 0.4	1.6 ± 0.2	0.85 ± 0.15	0.25	0.85	1.50
			1.25 ± 0.20			
			1.60 ± 0.20			
1210	3.2 ± 0.5	2.5 ± 0.3	2.5 ± 0.3	0.25	1.00	1.20

OUTLINES



CAPACITANCE RANGE & THICKNESS FOR X7R

Table 2 Size 0805

CAP.	0805				
	10 V	16 V	25 V	50 V	100 V
1.0 nF	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15
1.5 nF	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15
2.2 nF	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15
3.3 nF	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15
4.7 nF	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15
6.8 nF	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15
10 nF	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15
15 nF	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15
22 nF	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15
33 nF	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	1.25±0.2
47 nF	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	1.25±0.2
68 nF	0.85±0.15	0.85±0.15	0.85±0.15	1.25±0.2	1.25±0.2
100 nF	0.85±0.15	0.85±0.15	0.85±0.15	1.25±0.2	1.25±0.2

NOTE

Values in shaded cells indicate thickness class in mm

CAPACITANCE RANGE & THICKNESS FOR X7R

Table 3 Size 1206

CAP.	1206						
	6.3 V	10V	16V	25V	50 V	100 V	250 V
22 nF	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	1.25±0.2
33 nF	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	1.25±0.2
47 nF	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	1.25±0.2
68 nF	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	1.25±0.2	1.25±0.2
100 nF	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	0.85±0.15	1.25±0.2	1.6±0.2
150 nF	1.25±0.2	1.25±0.2	1.25±0.2	1.25±0.2	1.25±0.2	1.25±0.2	
220 nF	1.25±0.2	1.25±0.2	1.25±0.2	1.25±0.2	1.25±0.2	1.25±0.2	

Table 4 Size 1210

CAP.	1210
	50 V
4.7 uF	2.5±0.3

NOTE

Values in shaded cells indicate thickness class in mm

THICKNESS CLASSES AND PACKING QUANTITY

Table 5

SIZE CODE	THICKNESS CLASSIFICATION	TAPE WIDTH QUANTITY PER REEL	Ø180 MM / 7 INCH		Ø330 MM / 13 INCH	
			Paper	Blister	Paper	Blister
0805	0.85 ±0.15 mm	8 mm	4,000	---	15,000	---
	1.25 ±0.2 mm	8 mm	---	3,000	---	10,000
1206	0.6 ±0.1 mm	8 mm	4,000	---	20,000	---
	0.85 ±0.1 mm	8 mm	4,000	---	15,000	---
	1.25 ±0.2 mm	8 mm	---	3,000	---	10,000
	1.6 ±0.2 mm	8 mm	---	2,000	---	10,000
1210	2.5 ±0.3 mm	8 mm	---	1,000	---	---

ELECTRICAL CHARACTERISTICS

NP0/X7R DIELECTRIC CAPACITORS; NI/SIN TERMINATIONS

Unless otherwise specified, all test and measurements shall be made under standard atmospheric conditions for testing as given in 5.3 of IEC 60068-1:

- Temperature: 15 °C to 35 °C
- Relative humidity: 25% to 75%
- Air pressure: 86 kPa to 106 kPa

Before the measurements are made, the capacitor shall be stored at the measuring temperature for a time sufficient to allow the entire capacitor to reach this temperature.

The period as prescribed for recovery at the end of a test is normally sufficient for this purpose.

Table 6

DESCRIPTION					VALUE
Capacitance range					1 nF to 4.7 uF
Capacitance tolerance					
X7R					±5% (1), ±10%, ±20%
Dissipation factor (D.F.)					
X7R		0805	1206	1210	
	≤10V	1nF to 100uF	22nF to 200nF		≤ 5%
	16V	1nF to 100nF	22nF to 200nF		≤ 3.5%
		680nF to 1uF			≤ 5%
	25V	1nF to 100nF	22nF to 200nF		≤ 2.5%
	50V	1nF to 100nF	22nF to 220nF		≤ 2.5%
		220nF to 470nF			≤ 3.5%
				4.7 uF	≤ 5%
	100V	1nF to 100nF	22nF to 220nF		≤ 2.5%
					≤ 5%
	250V		22nF to 100nF		
Insulation resistance after 1 minute at U_r (DC)					IR ≥ 10 GΩ or I.R × C ≥ 500Ω.F whichever is less
Maximum capacitance change as a function of temperature (temperature characteristic/coefficient):					
X7R					±15%
Operating temperature range:					
X7R					–55 °C to +125 °C

NOTE

1. Capacitance tolerance ±5% doesn't available for X7R full product range, please contact local sales force before order

SOLDERING RECOMMENDATION

Table 7

SOLDERING METHOD	SIZE 0402	0603	0805	1206	≥ 1210
Reflow	≥ 0.1 μF	≥ 1.0 μF	≥ 2.2 μF	≥ 4.7 μF	Reflow only
Reflow/Wave	< 0.1 μF	< 1.0 μF	< 2.2 μF	< 4.7 μF	---

SOLDERING CONDITIONS

The lead free MLCCs are able to stand the reflow soldering conditions as below:

- Temperature: above 220 °C
- Endurance: 95 to 120 seconds
- Cycles: 3 times

The test of "soldering heat resistance" is carried out in accordance with the schedule of "MIL-STD-202F-method 210F", "The robust construction of chip capacitors allows them to be completely immersed in a solder bath of 270 °C for 10 seconds". Therefore, it is possible to mount MLCCs on one side of a PCB and other discrete components on the reverse (mixed PCBs). Surface Mount Capacitors are tested for solderability at 245 °C during 2 seconds. The test condition for no leaching is 260°C for 30 seconds.

TESTS AND REQUIREMENTS

Table 8 Test procedures and requirements

TEST	TEST METHOD		PROCEDURE	REQUIREMENTS
Mounting	IEC 60384-21/22	4.3	The capacitors may be mounted on printed-circuit boards or ceramic substrates	No visible damage
Capacitance	IEC 60384-21/22	4.5.1	Class 1: At 20°C, 24 hours after annealing f = 1 MHz for C ≤ 1nF, measuring at voltage 1 V_{rms} at 20°C f = 1 KHz for C > 1nF, measuring at voltage 1 V_{rms} at 20°C Class 2: At 20°C, 24 hours after annealing f = 1 KHz, measuring at voltage 1 V_{rms} at 20°C	Within specified tolerance
Dissipation Factor (D.F.)	IEC 60384-21/22	4.5.2	Class 1: At 20°C, 24 hours after annealing f = 1 MHz for C ≤ 1nF, measuring at voltage 1 V_{rms} at 20°C f = 1 KHz for C > 1nF, measuring at voltage 1 V_{rms} at 20°C Class 2: At 20 °C, 24 hours after annealing f = 1 KHz, measuring at voltage 1 V_{rms} at 20°C	In accordance with specification
Insulation Resistance	IEC 60384-21/22	4.5.3	At U_r (DC) for 1 minute	In accordance with specification

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Temperature coefficient	4.6	Capacitance shall be measured by the steps shown in the following table. The capacitance change should be measured after 5 min at each specified temperature stage. Step / Temperature(°C): a 25±2; b Lower temperature±3°C; c 25±2; d Upper Temperature±2°C; e 25±2 (1) Class I Temperature Coefficient shall be calculated from the formula as below $\text{Temp, Coefficient} = \frac{C2 - C1}{C1 \times \Delta T} \times 10^6$ [ppm/°C] C1: Capacitance at step c C2: Capacitance at 125°C ΔT: 100°C (=125°C -25°C) (2) Class II Capacitance Change shall be calculated from the formula as below $\Delta C = \frac{C2 - C1}{C1} \times 100\%$ C1: Capacitance at step c C2: Capacitance at step b or d	<General purpose series> Class1: Δ C/C: ±30ppm Class2: X7R: Δ C/C: ±15% <High Capacitance series> Class2: X7R/X5R: Δ C/C: ±15%
High Temperature Exposure	AEC-Q200 3	Unpowered ; 1000hours @ T=150°C Measurement at 24±2 hours after test conclusion.	No visual damage Δ C/C : Class1: NP0: within ±0.5% or 0.5 pF whichever is greater Class2: X7R: ±10% D.F.: within initial specified value IR: within initial specified value

TEST	TEST METHOD		PROCEDURE	REQUIREMENTS
Temperature Cycling	AEC-Q200	4	Preconditioning; 150 +0/–10°C for 1 hour, then keep for 24 ±1 hours at room temperature 1000 cycles with following detail: 30 minutes at lower category temperature 30 minutes at upper category temperature Recovery time 24 ±2 hours	No visual damage ΔC/C Class1: NP0: Within ±1% or 0.5pF, whichever is greater. Class2: X7R: ±10% D.F. meet initial specified value IR meet initial specified value
Destructive Physical Analysis	AEC-Q200	5	10ea X 3 lots. Note: Only applies to SMD ceramics. Electrical test not required.	
Moisture Resistance	AEC-Q200	6	T=24 hrs/per cycle; 10 continuous cycles unpowered. Measurement at 24 ±2 hours after test condition.	No visual damage ΔC/C NP0: Within ±3% or 3 pF, whichever is greater X7R: ±10% D.F. Within initial specified value IR NP0: ≥ 10,000 MΩ X7R: Meet initial specified value

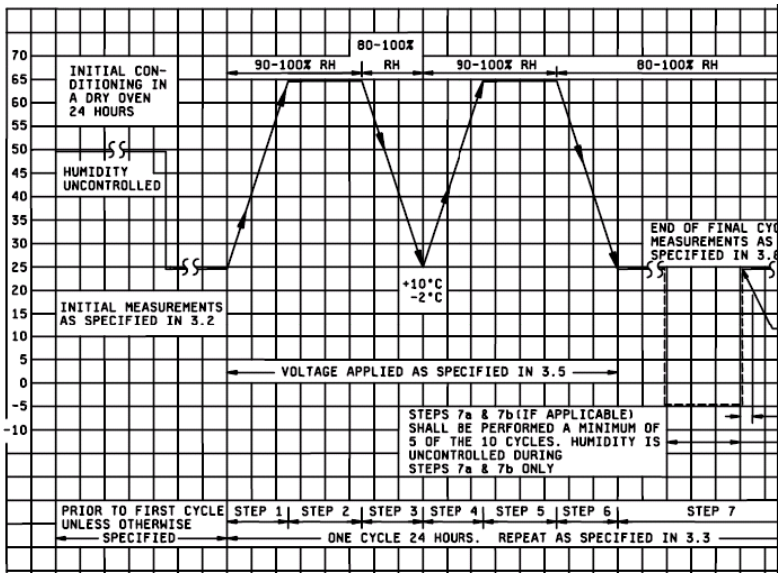
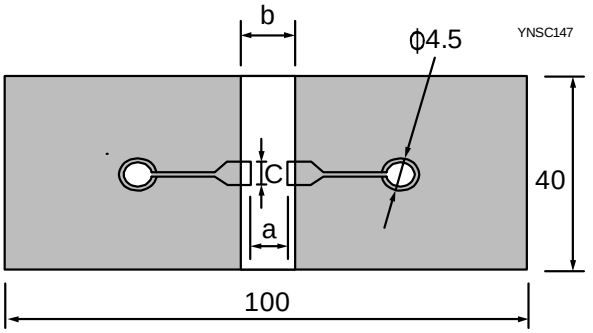


Fig. 4 Moisture resistant

TEST	TEST METHOD	PROCEDURE	REQUIREMENTS
Biased Humidity	AEC-Q200 7	1. Preconditioning, class 2 only: 150 +0/-10 °C /1 hour, then keep for 24 ±1 hour at room temp 2. Initial measure: Parameter: IR Measuring voltage: 1.5V ± 0.1 VDC Note: Series with 100 KΩ & 6.8 KΩ 3. Test condition: 85 °C, 85% R.H. connected with 100 KΩ resistor, applied 1.5V/U_r for 1,000 hours. 4. Recovery: Class1: 6 to 24 hours Class2: 24 ±2 hours 5. Final measure: IR	No visual damage after recovery Initial requirement: Class1: - Connected to 100 KΩ: C ≤ 10 nF: I.R ≥ 10,000 MΩ or C > 10 nF: (I.R-100 KΩ) x C ≥ 100s. - Connected to 6.8 KΩ: C ≤ 10 nF: I.R ≥ 10,000 MΩ or C > 10 nF: (I.R-6.8 KΩ) x C ≥ 100s. Class2: - Connected to 100 KΩ: C ≤ 25 nF: I.R ≥ 4,000 MΩ or C > 25 nF: (I.R-100 KΩ) x C ≥ 100s. - Connected to 6.8 KΩ: C ≤ 25 nF: I.R ≥ 10,000 MΩ or C > 25 nF: (I.R-6.8 KΩ) x C ≥ 100s. Final measurement: The insulation resistance shall be greater than 0.1 time initial value.

TEST	TEST METHOD		PROCEDURE	REQUIREMENTS
Operational Life	AEC-Q200	8	1. Preconditioning, class 2 only: 150 +0/-10 °C /1 hour, then keep for 24 ±1 hour at room temp 2. Initial measure: Spec: refer to initial spec C, D, IR 3. Endurance test: Temperature: X7R: 125 °C Specified stress voltage applied for 1,000 hours: Applied 2.0 x U_r for general products Applied 1.5 x U_r for high cap. Products High voltage series follows with below stress condition: Applied 1.5 x Ur for 200V, 250V series Applied 1.3 x Ur for 500V, 630V series Applied 1.2 x Ur for 1KV, 2KV, 3KV series 4. Recovery time: 24 ±2 hours 5. Final measure: C, D, IR Note: If the capacitance value is less than the minimum value permitted, then after the other measurements have been made the capacitor shall be preconditioned according to *"IEC 60384 4.1"* and then the requirement shall be met.	No visual damage ΔC/C NP0: Within ±2% or 1 pF, whichever is greater X7R: ±15% D.F. NP0: ≤ 2 x specified value. X7R: ≤ 16V: ≤ 7% ≥ 25V: ≤ 5% IR NP0: ≥ 4,000 MΩ or IR x C_r ≥ 40s whichever is less X7R: ≥ 1,000 MΩ or IRx C_r ≥ 50s whichever is less
External Visual	AEC-Q200	9	Any applicable method using × 10 magnification	In accordance with specification
Physical Dimension	AEC-Q200	10	Verify physical dimensions to the applicable device specification.	In accordance with specification
Mechanical Shock	AEC-Q200	13	Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks) Peak value: 1,500 g's Duration: 0.5 ms Velocity change: 15.4 ft/s Waveform: Half-sin	ΔC/C NP0: Within ±0.5% or 0.5 pF, whichever is greater X7R: ±10% D.F. Within initial specified value IR Within initial specified value
Vibration	AEC-Q200	14	5 g's for 20 minutes, 12 cycles each of 3 orientations. Note: Use 8" x 5" PCB. 0.31" thick 7 secure points on one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10-2000 Hz.	ΔC/C NP0: Within ±0.5% or 0.5 pF, whichever is greater X7R: ±10% D.F: meet initial specified value IR meet initial specified value

TEST	TEST METHOD		PROCEDURE	REQUIREMENTS
Resistance to Soldering Heat	AEC-Q200	15	Precondition: 150 +0/–10 °C for 1 hour, then keep for 24 ±1 hours at room temperature Preheating: for size ≤ 1206: 120 °C to 150 °C for 1 minute Preheating: for size >1206: 100 °C to 120 °C for 1 minute and 170 °C to 200 °C for 1 minute Solder bath temperature: 260 ±5 °C Dipping time: 10 ±0.5 seconds Recovery time: 24 ±2 hours	Dissolution of the end face plating shall not exceed 25% of the length of the edge concerned ΔC/C Class1: NP0: Within ±1% or 0.5 pF, whichever is greater. Class2: X7R: ±10% D.F. within initial specified value IR within initial specified value
Thermal Shock	AEC-Q200	16	1. Preconditioning, class 2 only: 150 +0/-10 °C /1 hour, then keep for 24 ±1 hour at room temp 2. Initial measure: Spec: refer to initial spec C, D, IR 3. Rapid change of temperature test: NP0/X7R: -55 °C to +125 °C; 300 cycles 15 minutes at lower category temperature; 15 minutes at upper category temperature. 4. Recovery time: Class1: 6 to 24 hours Class2: 24 ±2 hours 5. Final measure: C, D, IR	No visual damage ΔC/C NP0: Within ±1% or 1 pF, whichever is greater X7R: ±15% D.F: meet initial specified value IR meet initial specified value
ESD	AEC-Q200	17	Per AEC-Q200-004	A component passes a voltage level if all components stressed at that voltage level pass. HBM > 4kV
Solderability	AEC-Q200	18	Preheated to a temperature of 80 °C to 140 °C and maintained for 30 seconds to 60 seconds. Test conditions for lead containing solder alloy Temperature: 235 ±5 °C Dipping time: 2 ±0.2 seconds Depth of immersion: 10 mm Alloy Composition: 60/40 Sn/Pb Number of immersions: 1 Test conditions for lead-free containing solder alloy Temperature: 245 ±5 °C Dipping time: 3 ±0.3 seconds Depth of immersion: 10 mm Alloy Composition: SAC305 Number of immersions: 1	The solder should cover over 95% of the critical area of each termination.

TEST	TEST METHOD		PROCEDURE	REQUIREMENTS
Electrical Characterization	AEC-Q200	19	Parametrically test per lot and sample size requirements, summary to show Min, Max, Mean and Standard deviation at room as well as Min and Max operating temperatures. Class 1: NP0: -55 °C to +125 °C Normal temperature: 20 °C Class 2: X7R: -55 °C to +125 °C Normal temperature: 20 °C	ΔC/C Class 1: NP0: ±30 ppm/°C Class2: X7R: ±15%
Board Flex	AEC-Q200	21	Part mounted on a 100 mm X 40 mm FR4 PCB board, which is 1.6 ±0.2 mm thick and has a layer-thickness 35 µm ± 10 µm. Part should be mounted using the following soldering reflow profile. Conditions: Class2: Bending 5 mm at a rate of 1 mm/s, radius jig 230 mm Test Substrate:  unit: mm	No visible damage ΔC/C Class2: X7R: ±10%
Terminal Strength	AEC-Q200	22	With the component mounted on a PCB obtained with the device to be tested, apply a 17.7N (1.8Kg) force to the side of a device being tested. This force shall be applied for 60+1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested. * Apply 2N force for 0402 size.	Magnification of 20X or greater may be employed for inspection of the mechanical integrity of the device body, terminals and body/terminal junction. Before, during and after the test, the device shall comply with all electrical requirements stated in this specification.

	Dimension(mm)		
Type	a	b	c
0201	0.3	0.9	0.3
0402	0.4	1.5	0.5
0603	1.0	3.0	1.2
0805	1.2	4.0	1.65
1206	2.2	5.0	1.65
1210	2.2	5.0	2.0
1808	3.5	7.0	3.7

TEST	TEST METHOD		PROCEDURE	REQUIREMENTS
Beam Load Test	AEC-Q200	23	Place the part in the beam load fixture. Apply a force until the part breaks or the minimum acceptable force level required in the user specification(s) is attained.	≤ 0805 Thickness > 0.5 mm: 20N Thickness ≤ 0.5 mm: 8N ≥ 1206 Thickness ≥1.25 mm: 54N Thickness < 1.25 mm: 15N
Voltage Proof	IEC 60384-1	4.6	Specified stress voltage applied for 1~5 seconds Ur ≤ 100 V: series applied 2.5 Ur 100 V < Ur ≤ 200 V series applied (1.5 Ur + 100) 200 V < Ur ≤ 500 V series applied (1.3 Ur + 100) Ur > 500 V: 1.3 Ur Ur ≥ 1000 V: 1.2 Ur Charge/Discharge current is less than 50mA	No breakdown or flashover

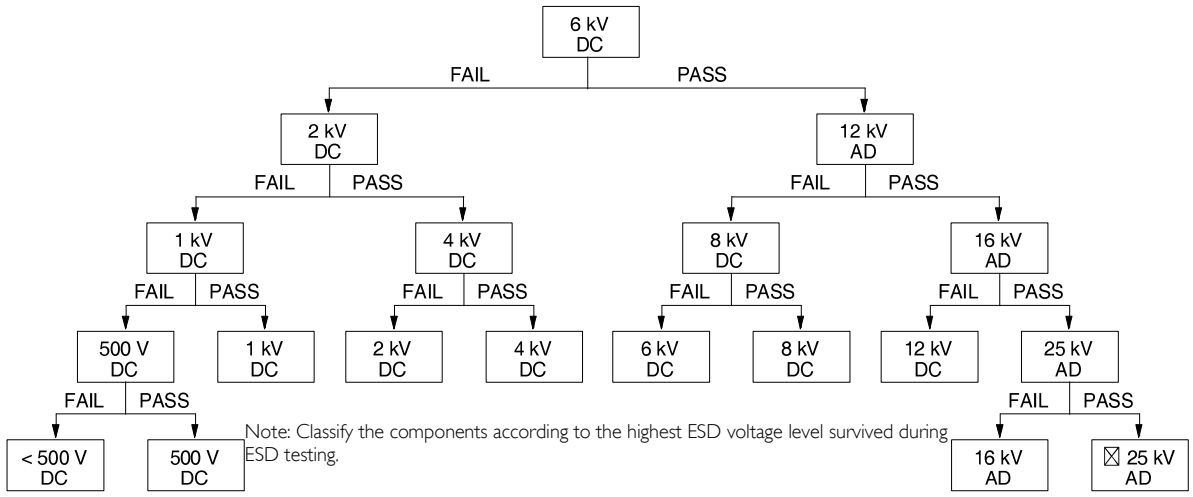


Fig. 5 Passive component HBM ESD test flow diagram (DC = Direct Contact Discharge, AD = Air Discharge)

REVISION HISTORY

REVISION	DATE	CHANGE NOTIFICATION	DESCRIPTION
Version 0	Oct. 05, 2017	-	- New

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